



TEI0022 TRM

Revision v.54

Exported on 2020-11-03

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4 Overview

The Trenz Electronic TEI0022 is a SoC board based on Intel Cyclone V FPGA, an Ethernet PHY, one GByte DDR3 SDRAM per HPS and FPGA and one 32 MByte Quad SPI Flash memory for configuration and operation per HPS and FPGA, and powerful switching-mode power supplies for all on-board voltages.

Refer to <http://trenz.org/tei0022-info> for the current online version of this manual and other available documentation.

4.1 Key Features

- **SoC FPGA**
 - Intel Cyclone V (5CSEMA5F31C8N)
 - Package: FBGA 896 pins
 - Speed Grade: 8
 - Temperature: Commercial (Tj = 0 °C to 85 °C)
- **RAM/Storage**
 - 1 GByte DDR3 SDRAM for HPS
 - 1 GByte DDR3 SDRAM for FPGA
 - 32 MByte SPI for HPS
 - 32 MByte SPI for FPGA
- **On Board**
 - up to 7 x SMA Connector
 - Temperature Sensor
 - Intel MAX10 for board management
- **Interface**
 - LPC FMC Connector
 - 4 x Pmod Connector
 - JTAG
 - UART via micro USB B Connector (for FPGA)
 - UART via micro USB B Connector (for HPS)
 - 4 x USB 2.0 Host
 - Ethernet via RJ45 Connector
 - SD Card
 - HDMI
- **Power**
 - 12 V Input supply voltage
- **Dimension**
 - 160 mm x 130 mm

4.2 Block Diagram

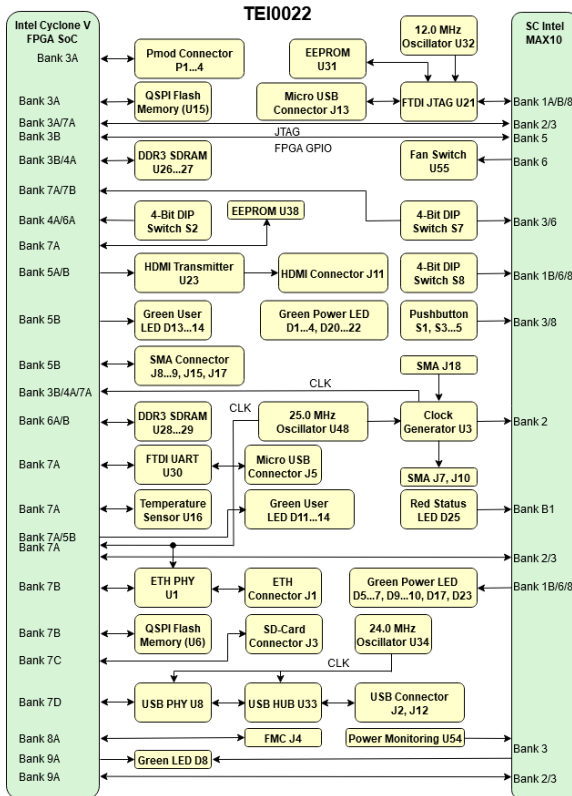


Figure 1: TEI0022 block diagram

4.3 Main Components

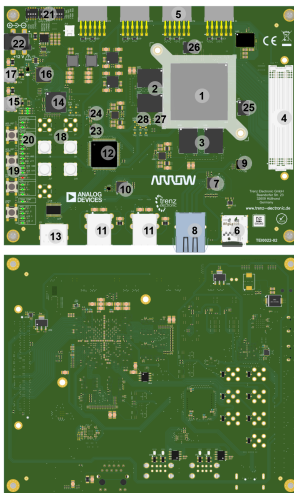


Figure 2: TEI0022 main components

1. Intel Cyclone V, U10
2. DDR3 SDRAM, U26...27
3. DDR3 SDRAM, U28...29
4. FMC, J4
5. Pmod, P1...4
6. SD Card Connector, J3
7. Ethernet PHY, U1

8. RJ45 Connector, J1
9. USB PHY, U8
10. USB HUB, U33
11. USB Connector, J2, J12
12. HDMI Transmitter, U23
13. HDMI Connector, J11
14. Intel MAX10, U41
15. Micro USB to UART Interface, J5, U30
16. USB to JTAG, U21
17. Micro USB JTAG and UART, J13
18. SMA Connector
19. Push Button, S1, S3...5
20. LED
21. 4-Bit DIP Switch, S2, S7...8
22. 12 V Power Jack, J6
23. Clock Generator, U48
24. Programmable Clock Generator, U3
25. QSPI - FPGA PS, U6
26. QSPI - FPGA PL, U15
27. Temperature Sensor, U16
28. EEPROM, U38

4.4 Initial Delivery State

Storage device name	Content	Notes
HPS SPI Flash (U6)	Not programmed	HPS Configuration
FPGA SPI Flash (U15)	Not programmed	FPGA Configuration
MAC EEPROM (U38)	MAC programmed, otherwise not programmed	Ethernet MAC
FTDI EEPROM (U31)	Programmed	FTDI Functionality

Table 1: Initial delivery state of programmable devices on the module

4.5 Configuration Signals

BOOTSEL[1..0] Signal State	DIP-switch S7 position	Boot Mode	Notes
00	S7A - ON; S7B - ON	FPGA	
01	S7A - ON; S7B - OFF	SD	

BOOTSEL[1..0] Signal State	DIP-switch S7 position	Boot Mode	Notes
11	S7A - OFF; S7B - OFF	SPI	

Table 2: Boot process.

Reset	Button	Note
HPS cold reset	S1	
HPS warm reset	S3	
FPGA reset	S4	

Table 3: Reset process.

5 Signals, Interfaces and Pins

5.1 FMC LPC Connector

The FMC (FPGA Mezzanine Card) connector J4 with low pin count (LPC) provides as an ANSI/VITA 57.1 standard a modular interface to the Intel Cyclone V FPGA and exposes numerous of its I/O pins for use by other mezzanine modules and expansion cards.

The connector supports single ended (VCCIO: FMC_VADJ) and differential signaling as the I/O's are routed from the FPGA banks as LVDS-pairs to the FMC connector.

FMC Signal	Intel Cyclone V Direction	I/O Signal Count (Single Ended/Differential)	Voltage Level	Notes
LA0...1	RX	4 / 2	FMC_VA DJ	Voltage level as visible in table Intel Cyclone V SoC bank voltages .
LA3, LA5, LA7, ..., LA33	RX	32 / 16	FMC_VA DJ	Voltage level as visible in table Intel Cyclone V SoC bank voltages .
LA2, LA4, LA6, ..., LA32	TX	32 / 16	FMC_VA DJ	Voltage level as visible in table Intel Cyclone V SoC bank voltages .
CLK0...1	RX	4 / 2	FMC_VA DJ	Voltage level as visible in table Intel Cyclone V SoC bank voltages .

Table 4: FMC connectors information

The FMC connector provides further interfaces like JTAG and I²C:

Interface	I/O Signal Count	Pin schematic Names / FMC Pins	Connected to	Notes
JTAG	5	FMC_TCK, Pin J4-D29 FMC_TMS, Pin J4-D33 FMC_TDI, Pin J4-D30 FMC_TDO, Pin J4-D31 FMC_TRST#, Pin J4-D34	Intel MAX10 U41, Bank 3	VCCIO: +3.3V
I2C	2	FMC_SCL, Pin J4-C30 FMC_SDA, Pin J4-C31	Intel MAX10 U41, Bank 3 and Intel Cyclone V U10, Bank 7A	I2C-lines pulled-up to +3.3V
Control Lines	2	FMC_PRSENT_M2C#, Pin J4-H2 (pulled-up to +3.3V) FMC_PG_C2M, Pin J4-D1 (pulled-up to +3.3V)	Intel MAX10 U41, Bank 3 and Intel Cyclone V U10, Bank 5B / 7C	'PG' = 'Power Good'-signal 'C2M' = carrier to (Mezzanine) module 'M2C' = (Mezzanine) module to carrier

Table 5: FMC connector pin-outs of available interfaces

Several VCCIO voltages are available on the FMC connector to operate the I/O's on different voltage levels:

VCCIO Schematic Name	FMC Connector J4 Pins	Notes
+12.0V_FMC	C35/C37	extern 12 V power supply
+3.3V_FMC	D36/D38/D40/C39	3.3 V peripheral supply voltage
+3.3V	D32	3.3 V peripheral supply voltage

VCCIO Schematic Name	FMC Connector J4 Pins	Notes
FMC_VADJ	H40/G39	adjustable FMC VCCIO voltage, supplied by DC-DC converter U43
FMC_VREF_A_M2C	H1	adjustable reference voltage

Table 6: Available VCCIO voltages on FMC connector

5.2 Pmod Connector

The TEI0022 board offers four Pmod (2x6 pins, SMD) connectors which provides as a standard modular interface single ended I/O pins for use with extension modules.

Following table gives an overview of the Pmod connectors and the signals routed to the attached Intel Cyclone V (U10):

Pmod Connector P1 Pin	Signal Schematic Name	Connected to Intel Cyclone V, U10	Notes
1	P0_IO1	Pin AD9	
2	P0_IO2	Pin AD11	
3	P0_IO3	Pin AD12	
4	P0_IO4	Pin AC12	
7	P0_IO5	Pin AC9	
8	P0_IO6	Pin AD10	
9	P0_IO7	Pin AA12	
10	P0_IO8	Pin AB12	
Pmod Connector P2 Pin	Signal Schematic Name	Connected to Intel Cyclone V, U10	Notes
1	P1_IO1	Pin AG2	
2	P1_IO2	Pin AF4	
3	P1_IO3	Pin AF8	
4	P1_IO4	Pin AD7	
7	P1_IO5	Pin AG1	

Pmod Connector P1 Pin	Signal Schematic Name	Connected to Intel Cyclone V, U10	Note s
8	P1_IO6	Pin AF5	
9	P1_IO7	Pin AE7	
10	P1_IO8	Pin AE9	
Pmod Connector P3 Pin	Signal Schematic Name	Connected to Intel Cyclone V, U10	Note s
1	P2_IO1	Pin AH5	
2	P2_IO2	Pin AH3	
3	P2_IO3	Pin AJ2	
4	P2_IO4	Pin AG3	
7	P2_IO5	Pin AG5	
8	P2_IO6	Pin AH4	
9	P2_IO7	Pin AH2	
10	P2_IO8	Pin AJ1	
Pmod Connector P4 Pin	Signal Schematic Name	Connected to Intel Cyclone V, U10	Note s
1	P3_IO1	Pin AE12	
2	P3_IO2	Pin AF9	
3	P3_IO3	Pin AG8	
4	P3_IO4	Pin AG6	
7	P3_IO5	Pin AE11	
8	P3_IO6	Pin AF10	
9	P3_IO7	Pin AG7	
10	P3_IO8	Pin AF6	

Table 7: Pmod connectors pin description

5.3 SMA Connector

The TEI0022 board offers up to seven SMA connectors for trigger and clock input and output.

SMA Connector	Signal Schematic Names	Connected to	Notes
J7	SMA_CLK_OUT_p	Clock Generator U3, Pin 22	Assembly option
J10	SMA_CLK_OUT_n	Clock Generator U3, Pin 21	Assembly option
J8	TRIGGER_OUTPUT	Intel Cyclone V U10, Pin AE29	
J9	TRIGGER_INPUT	Intel Cyclone V U10, Pin AA26	
J15	EXT_CLK_INPUT	Intel Cyclone V U10, Pin Y26	
J17	CLK_INPUT	Intel Cyclone V U10, Pin AD29	
J18	SMA_CLK_IN	Clock Generator U3, Pin 1	Assembly option

Table 8: SMA connectors

5.4 FAN Connector

The TEI0022 board offers a FAN connector for cooling the FPGA device. Depending on the assembly 5 V or 12 V are usable.

Connector	Signal Schematic Names	Connected to	Notes
2-Pin FAN Connector J16, 5 V or 12 V power supply depending on R270/271 with BTS4141N High Side Switch U55	FAN_EN, (High Side Switch U55, Pin 3)	Intel MAX10 U41, Pin D13	Intel Cyclone V cooling FAN

Table 9: FAN connectors

5.5 Micro USB Connector (JTAG)

According to the JTAGEN and JTAGSEL[1..0] pins the management controller Intel MAX10 (U41), the Intel Cyclone V HPS (U10), the Intel Cyclone V FPGA (U10) or the FMC (J4) can be accessed via the micro USB B connector J13.

JTAGSEL1	JTAGSEL0	JTAGSEL1	JTAGSEL0	Note
X	X	ON	Intel MAX10	
ON	ON	OFF	Intel Cyclone V HPS	
ON	OFF	OFF	Intel Cyclone V FPGA	
OFF	ON	OFF	FMC	

Table 10: JTAG pins connection

TEI0022 - JTAG

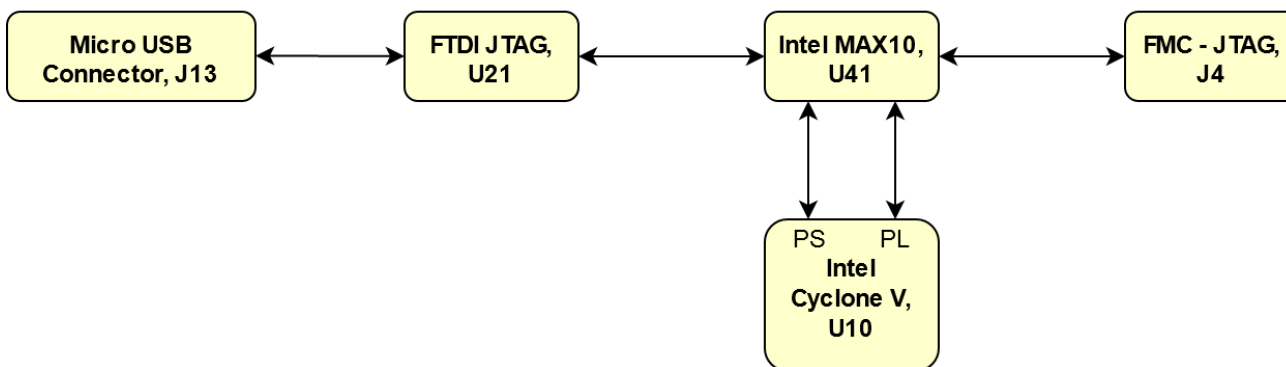


Figure 3: TEI0022 JTAG

5.6 Micro USB Connector (UART)

A UART connection between the USB B connector J5 and the Intel Cyclone HPS U10 is possible via the FT234XD (U30) chip.

5.7 USB Connector

On the TEI0022 board there are up to four USB 2.0 Hi-Speed ports available (J2, J12).

5.8 HDMI Connector

The TEI0022 provides an HDMI Connector J11.

5.9 SD Card Connector

SD Card connector J3 is connected to the Intel Cyclone V U10.

5.10 RJ45 Connector

The board TEI0022 provides an ethernet interface via the RJ45 connector J1.

5.11 I2C

The TEI0022 provides three independent I2C busses. One bus is used to connect the FMC I2C with the Intel Cyclone V HPS. The second bus is used to connect the HDMI device to the Intel Cyclone V FPGA. The third bus is used to handle the other on-board I2C devices. Via assembly option, it is possible to connect bus two to bus three.

Bus	I2C Device	Designator	I2C Address	Schematic Names of I2C Bus Lines	Notes
HPS I2C	Temperature Sensor	U16	0x4A	HPS_I2C_SCL / HPS_I2C_SDA	3.3 V reference voltage
HPS I2C	Programmable Clock Generator	U3	0x70	HPS_I2C_SCL / HPS_I2C_SDA	3.3 V reference voltage
HPS I2C	EEPROM	U38	0x50	HPS_I2C_SCL / HPS_I2C_SDA	3.3 V reference voltage
HDMI I2C	HDMI	U23	0x72	HDMI_I2C_SCL / _I2C_SDA	3.3 V reference voltage
HPS FMC I2C	FMC	J4	0x50	FMC_SCL / FMC_SDA	3.3 V reference voltage

Table 11: On-board peripherals' I2C-interfaces device slave addresses

TEI0022 - I2C

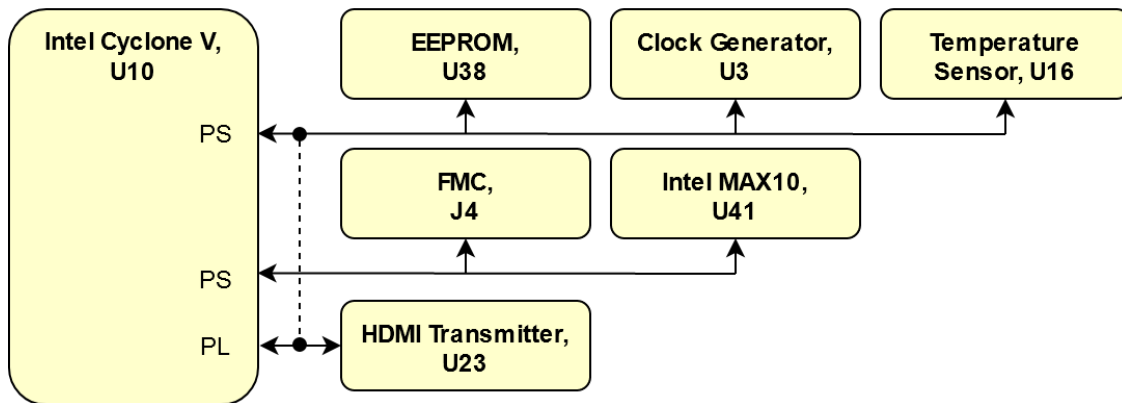


Figure 4: TEI0022 I2C

6 On-board Peripherals

Chip/Interface	Designator	Notes
System Controller Intel MAX10(see page 18)	U41	
Intel Cyclone V(see page 19)	U10	
DDR3 SDRAM(see page 19)	U26...29	
Gigabit Ethernet PHY(see page 19)	U1	
High-Speed USB ULPI PHY(see page 20)	U8	
4-Port USB 2.0 Hub(see page 20)	U33	
HDMI Transmitter(see page 21)	U23	
FTDI (JTAG)(see page 21)	U21	
FTDI (UART)(see page 22)	U30	
DIP-Switches(see page 22)	S2, S7...8	
Buttons(see page 23)	S1, S3...5	
On-Board LEDs(see page 23)	D1...15, D17...23, D25	
Temperature Sensor(see page 25)	U16	
QSPI(see page 25)	U6, U15	
EEPROM(see page 26)	U31, U38	
Oscillator(see page 26)	U32, U34, U48	
Programmable Clock Generator(see page 27)	U3	
Power Monitoring(see page 28)	U54	

Table 12: On board peripherals

6.1 System Controller Intel MAX 10

The TEI0022 is equipped with an Intel MAX 10 (U41) which is the central system management unit where essential control signals are logically linked by the implemented logic of the FPGA firmware. This generates output signals to control the system, the on-board peripherals and the interfaces. Interfaces like JTAG are by-passed, forwarded and controlled by the System Controller. Other tasks of the System Controller are the monitoring of the power-on

sequence and configuration of the Intel Cyclone V FPGA. The functionalities and configuration of the pins depend on its firmware.

6.2 Intel Cyclone V

The Intel Cyclone V device used at the TEI0022 board is a SoC with integrated ARM-based HPS. The 5CSEMA5F31C8N version delivers one hard memory controller, 80K logic elements in an FineLineBGA (FBGA) with 896 pins for the commercial temperature range of $T_J = 0...85\text{ }^{\circ}\text{C}$ with speed grade eight.

6.3 DDR3 SDRAM

The TEI0022 SoM has one GByte volatile DDR3 SDRAM memory per FPGA (U26, U27) and HPS (U28, U29) for storing user application code and data.

- Part number: IS43TR16256BL-125KBLI
- Supply voltage: 1.5 V
- Speed: TBD
- Temperature: $TC = -40\text{ }^{\circ}\text{C}$ up to $95\text{ }^{\circ}\text{C}$

6.4 Gigabit Ethernet PHY

On-board Gigabit Ethernet PHY (U1) is provided with Analog Devices ADIN1300. The Ethernet PHY RGMII interface is connected to the Intel Cyclone V HPS. I/O voltage is fixed at 3.3 V. The reference clock input of the PHY is supplied from the on-board 25.0 MHz oscillator (U48).

Bank	Signal Name	Signal Description
7B	ETH_TXCK	RGMII Transmit Reference Clock
7B	ETH_TXD0	RGMII Transmit Data 0
7B	ETH_TXD1	RGMII Transmit Data 1
7B	ETH_TXD2	RGMII Transmit Data 2
7B	ETH_TXD3	RGMII Transmit Data 3
7B	ETH_TXCTL	RGMII Transmit Control
7B	ETH_RXCK	RGMII Receive Reference Clock
7B	ETH_RXD0	RGMII Receive Data 0
7B	ETH_RXD1	RGMII Receive Data 1
7B	ETH_RXD2	RGMII Receive Data 2

Bank	Signal Name	Signal Description
7B	ETH_RXD3	RGMII Receive Data 3
7B	ETH_RXCTL	RGMII Receive Control
7C	ETH_RST	Reset
7B	ETH_MDC	Management Data Clock
7B	ETH_MDIO	Management Data I/O
7B	PHY_INT	Interrupt

Table 13: Ethernet PHY to HPS connections

6.5 High-Speed USB ULPI PHY

USB PHY (U8) is provided by USB3320C from Microchip. The ULPI interface is connected to the Intel Cyclone V HPS. I/O voltage is fixed at 3.3 V and PHY reference clock input is supplied from the on-board 24.0 MHz oscillator (U34).

PHY Pin	Connected to	Notes
ULPI	Intel Cyclone V HPS (U10)	
REFCLK	24 MHz from on board oscillator (U34)	
REFSEL[0..2]	High (3.3 V)	
RESETB	Intel Cyclone V HPS (U10) and Intel MAX 10 (U41)	
DP, DM	4-port USB 2.0 Hub (U33)	
CPEN	Not Connected.	
VBUS	Pull-up to 5 V.	
ID	Not Connected.	

Table 14: USB PHY interface connections

6.6 4-Port USB 2.0 Hub

On the TEI0022 board there are up to four USB 2.0 Hi-Speed ports available (J2, J12). The USB 2.0 ports are provided by Microchip Cypress USB2514B 4-port USB 2.0 Hub controller (U33) which is connected to the USB PHY USB3320C (U8) connected to the Intel Cyclone V HPS via ULPI.

6.7 HDMI Transmitter

The TEI0022 board provides an HDMI interface routed to the Intel Cyclone FPGA (U10). The HDMI interface is created by the HDMI transmitter ADV7511 provided by Analog Devices. The HDMI transmitter is incorporated in conjunction with the HDMI protection circuit TI TPD12S016 for more signal robustness.

HDMI connector J11	Signal Schematic Name	Connected to	Notes
Pin 1, 3	HDMI_TX2_P / HDMI_TX2_N	HDMI transmitter, Pin 43, 42	also connected to HDMI protection circuit
Pin 4, 6	HDMI_TX1_P / HDMI_TX1_N	HDMI transmitter, Pin 40, 39	also connected to HDMI protection circuit
Pin 7, 9	HDMI_TX0_P / HDMI_TX0_N	HDMI transmitter, Pin 36, 35	also connected to HDMI protection circuit
Pin 10, 12	HDMI_TXC_P / HDMI_TXC_N	HDMI transmitter, Pin 33, 32	also connected to HDMI protection circuit
Pin 13	CEC_B	HDMI transmitter, Pin 48	HDMI CEC, wired through HDMI protection circuit
Pin 15	SCL_B	HDMI transmitter, Pin 53	HDMI I ² C clock line, wired through HDMI protection circuit
Pin 16	SDA_B	HDMI transmitter, Pin 54	HDMI I ² C data line, wired through HDMI protection circuit
Pin 19	HPD_B	HDMI transmitter, Pin 30	Hot Plug Detect, wired through HDMI protection circuit
Pin 18	5V_HDMI	HDMI protection circuit, Pin 13	5V supply voltage, wired through HDMI protection circuit

Table 15: HDMI connector signals and pins

6.8 FTDI (JTAG)

Please refer to the section "[Micro USB Connector \(JTAG\)](#)(see page 15)".

6.9 FTDI (UART)

Please refer to the section "[Micro USB Connector \(UART\)](#)(see page 15)".

6.10 DIP-Switches

There are three 4-bit DIP-switches present on the TEI0022 board to configure options and set parameters. The following section describes the functionalities of the particular switches.

DIP-Switch S2

The table below describes the functionalities of the switches of DIP-switch S2 at their single positions:

DIP-switch S2	Position ON	Position OFF	Notes
S4-1	HPS_SW1 is low	HPS_SW1 is high	User switch
S4-2	HPS_SW2 is low	HPS_SW2 is high	User switch
S4-3	FPGA_SW1 is low	FPGA_SW1 is high	User switch
S4-4	FPGA_SW2 is low	FPGA_SW2 is high	User switch

Table 16: DIP-switch S2 functionality description

DIP-Switch S7

The table below describes the functionalities of the switches of DIP-switch S7 at their single positions:

DIP-switch S7	Position ON	Position OFF	Notes
S7-1	HPS_SPI_SS/ BOOTSEL0 is low	HPS_SPI_SS/ BOOTSEL0 is high	Boot select (Firmware dependent)
S7-2	QSPI_CS/BOOTSEL1 is low	QSPI_CS/BOOTSEL1 is high	Boot select (Firmware dependent)
S7-3	JTAGSEL0 is low	JTAGSEL0 is high	JTAG select (Firmware dependent)
S7-4	JTAGSEL1 is low	JTAGSEL1 is high	JTAG select (Firmware dependent)

Table 17: DIP-switch S7 functionality description

DIP-Switch S8

The table below describes the functionalities of the switches of DIP-switch S8 at their single positions:

DIP-switch S8	Position ON	Position OFF	Notes
S8-1	VID0_SW is low	VID0_SW is high	FMC_VADJ selection (Firmware dependent)
S8-2	VID1_SW is low	VID1_SW is high	FMC_VADJ selection (Firmware dependent)
S8-3	VID2_SW is low	VID2_SW is high	FMC_VADJ selection (Firmware dependent)
S8-4	JTAGEN is high	JTAGEN is low	JTAG select

Table 18: DIP-switch S8 functionality description

6.11 Buttons

There are four buttons present on the TEI0022 board. The following section describes the functionalities of the particular buttons. The final functionality is set by the management Intel MAX10.

Button	Position ON	Position OFF	Notes
S1	HPS_RST#_SW is low	HPS_RST#_SW is high	Reset (cold) the Intel Cyclone V HPS (Firmware dependent)
S3	HPS_WARM_RST#_SW is low	HPS_WARM_RST#_SW is high	Reset (warm) the Intel Cyclone V HPS (Firmware dependent)
S4	FPGA_RST#_SW is low	FPGA_RST#_SW is high	Reset the Intel Cyclone V FPGA (Firmware dependent)
S5	USER_BTN_SW is low	USER_BTN_SW is high	User button (Firmware dependent)

Table 19: Buttons functionality description

6.12 On-Board LEDs

The TEI0022 board is equipped with several LEDs to signal current states and activities. The functionality of the LEDs D11...14 are user LEDs. The LED D8 shows the Intel Cyclone V configuration progress. LEDs D15, D18...19 shows the UART connection and the other LEDs mentioned in the table are supply power status LEDs.

Designator	Color	Connected to	Active Level	Note
D11	Green	Intel Cyclone V HPS	H	User LED
D12	Green	Intel Cyclone V HPS	H	User LED
D13	Green	Intel Cyclone V FPGA	H	User LED
D14	Green	Intel Cyclone V FPGA	H	User LED
D8	Green	Intel Cyclone V FPGA, Intel MAX 10	L	Status: Configuration "Done"
D15	Green	FT234XD	L	UART
D18	Green	UART TX	L	UART
D19	Green	UART RX	L	UART
D21	Green	+12.0V	H	Status of +12.0V voltage rail
D1	Green	+12.0V_FMC	H	Status of +12.0V_FMC voltage rail
D2	Green	+5.0V	H	Status of +5.0V voltage rail
D3	Green	+3.3V	H	Status of +3.3V voltage rail
D20	Green	+3.3V_MAX10	H	Status of +3.3V_MAX10 voltage rail
D22	Green	+3.3V_FMC	H	Status of +3.3V_FMC voltage rail
D4	Green	+2.5V	H	Status of +2.5V voltage rail

Designator	Color	Connected to	Active Level	Note
D5	Green	Intel MAX 10	H	Status of +1.8V voltage rail
D7	Green	Intel MAX 10	H	Status of VCC voltage rail
D9	Green	Intel MAX 10	H	Status of FMC_VADJ voltage rail
D6	Green	Intel MAX 10	H	Status of VDD_DDR_FPGA voltage rail
D23	Green	Intel MAX 10	H	Status of VDD_DDR_HPS voltage rail
D17	Green	Intel MAX 10	H	Status of VTT_DDR_FPGA voltage rail
D10	Green	Intel MAX 10	H	Status of VTT_DDR_HPS voltage rail
D25	Red	Intel MAX 10	H	Status

Table 20: On-board LEDs

6.13 Temperature Sensor

The temperature sensor ADT7410 (U16) is implemented on the TEI0022 board.

6.14 Quad SPI Flash Memory

Two 256 Mbit (32 MByte) Quad SPI Flash Memory (Micron MT25QL256ABA8E12, U6, U15) are provided for FPGA and HPS configuration file storage. After configuration process completes the remaining free memory can be used for application data storage. All four SPI data lines are connected to the FPGA or the HPS allowing x1, x2 or x4 data bus widths to be used. The maximum data transfer rate depends on the bus width and clock frequency.

Quad SPI Flash memory U6 is connected to the HPS bank 7B and U15 to FPGA bank 3A.

Signal Name	QSPI Flash Memory U6 Pin	FPGA Pin
QSPI_CS/BOOTSEL1	S#, Pin C2	Bank 7B, Pin A18
QSPI_CLK	C, Pin B2	Bank 7B, Pin D19
QSPI_DATA0	DQ0, Pin D3	Bank 7B, Pin C20

Signal Name	QSPI Flash Memory U6 Pin	FPGA Pin
QSPI_DATA1	DQ1, Pin D2	Bank 7B, Pin H18
QSPI_DATA2	DQ2, Pin C4	Bank 7B, Pin A19
QSPI_DATA3	DQ3, Pin D4	Bank 7B, Pin E19

Table 21: HPS Quad SPI interface signals and connections

Signal Name	QSPI Flash Memory U15 Pin	FPGA Pin
nCS0	S#, Pin C2	Bank 3A, Pin AB8
AS_DCK	C, Pin B2	Bank 3A, Pin U7
AS_DATA0	DQ0, Pin D3	Bank 3A, Pin AE6
AS_DATA1	DQ1, Pin D2	Bank 3A, Pin AE5
AS_DATA2	DQ2, Pin C4	Bank 3A, Pin AE8
AS_DATA3	DQ3, Pin D4	Bank 3A, Pin AC7

Table 22: FPGA Quad SPI interface signals and connections

6.15 EEPROM

The TEI0022 board contains two EEPROMs for configuration and general user purposes.

EEPROM Model	I2C Address	Designator	Memory Density	Purpose	Notes
24AA025E48T-I/OT	0x50	U38	2 KBit	Ethernet MAC	
93AA56BT-I/OT	-	U31	2 KBit	JTAG Configuration	

Table 23: On-board configuration EEPROMs overview

6.16 Oscillator

The board has following reference clocking sources provided by on-board oscillators:

Clock Source	Frequency	Signal Schematic Name	Clock Destination	Notes
U48, SiT8208AI	25.0 MHz	CLK_25MHz_R	Si5338A PLL U3, Pin 3 (IN3)	
		HPS_CLK1_25MHz	HPS Bank 7A U10, Pin D25	
		ETH_XTAL_IN	ETH PHY U1, Pin 9	
U32, SiT8208AI	12.0 MHz	OSCI	FT2232H U21, Pin 3	
U34, SiT8008BI	24.0 MHz	USB_CLK24_HUB	USB Hub U33, Pin 33	
		USB_CLK24_PHY	USB PHY U8, Pin 26	

Table 24: Reference clock signals

6.17 Programmable Clock Generator

There is a Silicon Labs I²C programmable quad PLL clock generator on-board (Si5338A, U3) to generate various reference clocks for the module.

Si5338A Pin	Signal Name / Description	Connected to	Direction	Notes
IN1	SMA_CLK_IN	SMA J18, Pin 1	Input	Assembly option dependent
IN2	SMA_CLK_IN	SMA J18, Pin 1	Input	Assembly option dependent
IN3	Reference input clock	U48, Pin 3	Input	25 MHz oscillator U48, SiT8208
IN4	-	GND	Input	I ² C slave device address LSB
IN5	-	Not Connected	Input	Not used
IN6	-	GND	Input	Not used
SCL	HPS_I2C_SCL	HPS I2C Bus U10, Pin H23	Input	I ² C interface muxed to Intel Cyclone V Slave address: 0x70.

Si5338A Pin	Signal Name / Description	Connected to	Direction	Notes
SDA	HPS_I2C_SDA	HPS I2C Bus U10, Pin A25	Input / Output	I ² C interface muxed to Intel Cyclone V Slave address: 0x70.
CLK0A/B	SMA_CLK_OUT_p/n	SMA J7/J10	Output	Clock to SMA connectors (Assembly option dependent)
CLK1A/B	CLK_B3B_p/n	U10, Pin AF14/15	Output	Clock to FPGA bank 3B
CLK2A	CLK_MAX10	U41, Pin H6	Output	Clock to Intel MAX 10 bank 2
CLK2B	HPS_CLK2	U10, Pin F25	Output	Clock to HPS bank 7A
CLK3A/B	CLK_B4A_p/n	U10, Pin AA16/AB17	Output	Clock to FPGA bank 4A

Table 25: Programmable quad PLL clock generator inputs and outputs

6.18 Power Monitoring

The TEI0022 uses a precision supply monitor (U54) for three voltages. Therefore, if one of the voltages browns out it should be realized and handled.

7 Power and Power-On Sequence

7.1 Power Supply

The maximum power consumption of this board mainly depends on the design which is running on the FPGA. Intel provides power estimator excel sheets to calculate power consumption.

7.2 Power Consumption

Power Input Pin	Typical Current
+12.0V_IN	TBD*

Table 26: Power Consumption

* TBD - To Be Determined

7.3 Power Distribution Dependencies

All on-board voltages of the TEI0022 are generated out of the extern applied 12 V power supply.

There are following dependencies how the initial 12V power supply is distributed to the on-board DC-DC converters, which power up further DCDC converters and the particular on-board voltages:

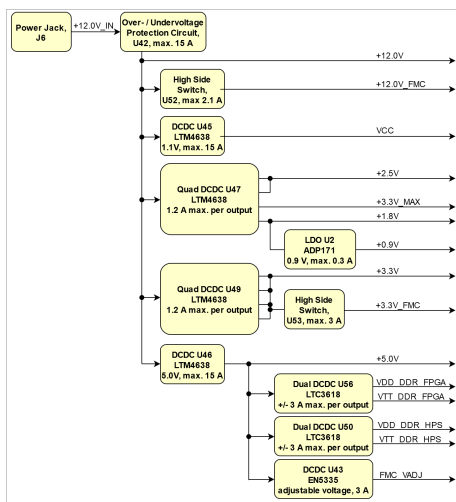


Figure 5: Power Distribution

7.4 Power-On Sequence

The following figures delivers the power-on sequence information. The figure [Power Sequence](#)(see figure 6) shows the connections between the power devices and its management. The figure [Suggested Power Sequence](#)(see figure 7)

shows the recommended firmware power-on sequence. For more information about firmware depended power-on sequencing see [TEI0022 Intel MAX 10 → Power mangement](https://wiki.trenz-electronic.de/display/PD/TEI0022+Intel+MAX+10#TEI0022IntelMAX10-Powermanagement)¹.

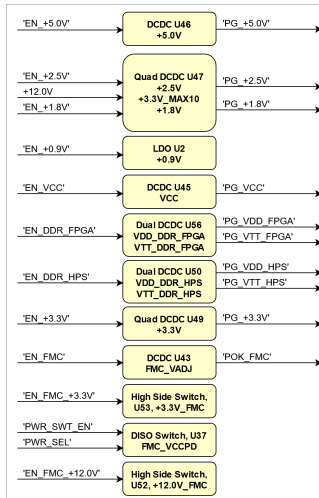


Figure 6: Power Sequence

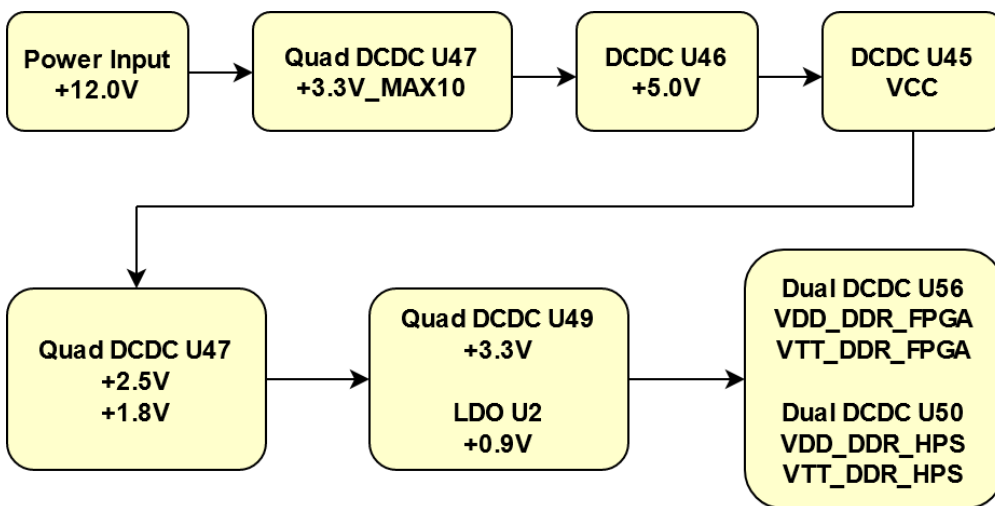


Figure 7: Suggested Power Sequence

7.5 Voltage Monitor Circuit

The voltages +3.3V, +5.0V, and VCC are monitored by the voltage monitor circuit LTC2911 (U54), which generates a reset signal at power-on. A manual reset is also possible as described in the [reset table](#).

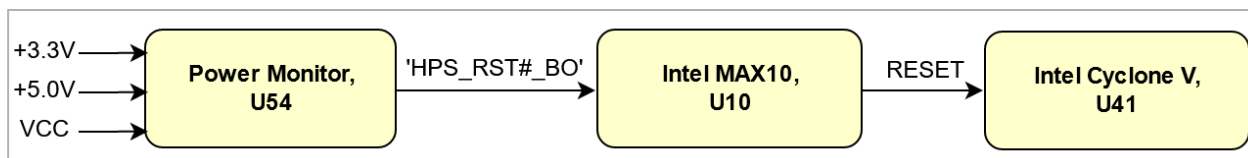


Figure 8: Voltage Monitor Circuit

¹ <https://wiki.trenz-electronic.de/display/PD/TEI0022+Intel+MAX+10#TEI0022IntelMAX10-Powermanagement>

7.6 Bank Voltages

Bank	Schematic Name	Voltage	Notes
Bank 3A	+3.3V	+3.3 V	
Bank 3B	VDD_DDR_FPGA	+1.5 V	
Bank 4A	VDD_DDR_FPGA	+1.5 V	
Bank 5A	+3.3V	+3.3 V	
Bank 5B	+3.3V	+3.3 V	
Bank 6A	VDD_DDR_HPS	+1.5 V	
Bank 6B	VDD_DDR_HPS	+1.5 V	
Bank 7A	+3.3V	+3.3 V	
Bank 7B	+3.3V	+3.3 V	
Bank 7C	+3.3V	+3.3 V	
Bank 7D	+3.3V	+3.3 V	
Bank 8A	FMC_VADJ	+3.3 V, +2.5 V, +1.8 V, +1.25 V, +1.2 V	Adjustable voltage (+0.8 V is not usable at the Intel Cyclone V)
Bank 9A	+3.3V	+3.3 V	

Table 27: Intel Cyclone V SoC bank voltages.

8 Technical Specifications

8.1 Absolute Maximum Ratings

Symbols	Description	Min	Max	Unit
+12.0V_IN	Input Voltage	-25	25	V

Table 28: PS absolute maximum ratings

8.2 Recommended Operating Conditions

Operating temperature range depends also on customer design and cooling solution. Please contact us for options.

Parameter	Min	Max	Units	Reference Document
+12.0V_IN	10.5	13	V	Input power protection U42

Table 29: Recommended operating conditions.

8.3 Physical Dimensions

- Module size: 160 mm × 130 mm. Please download the assembly diagram for exact numbers.

PCB thickness: 1.9 mm.

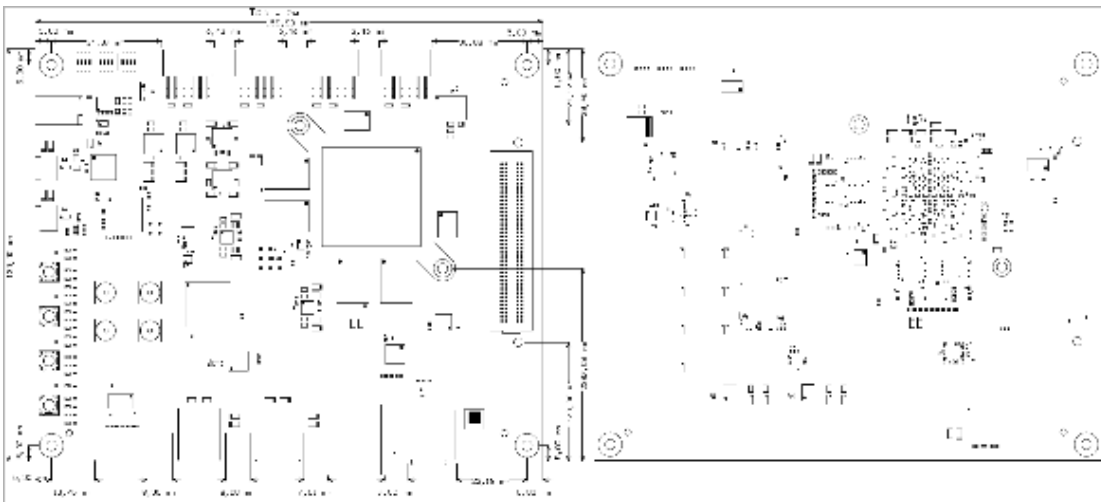


Figure 9: Physical Dimension

9 Currently Offered Variants

Trenz shop TEI0022 overview page	
English page²	German page³

Table 30: Trenz Electronic Shop Overview

² <https://shop.trenz-electronic.de/en/search?sSearch=tei0022>

³ <https://shop.trenz-electronic.de/de/search?sSearch=tei0022>

10 Revision History

10.1 Hardware Revision History

Date	Revision	Changes	Documentation Link
-	03	Refer to the "Revision_Changes" schematic page	
-	02	Refer to the "Revision_Changes" schematic page	
-	01	First Production Release	

Table 31: Hardware Revision History

Hardware revision number can be found on the PCB board together with the module model number separated by the dash.

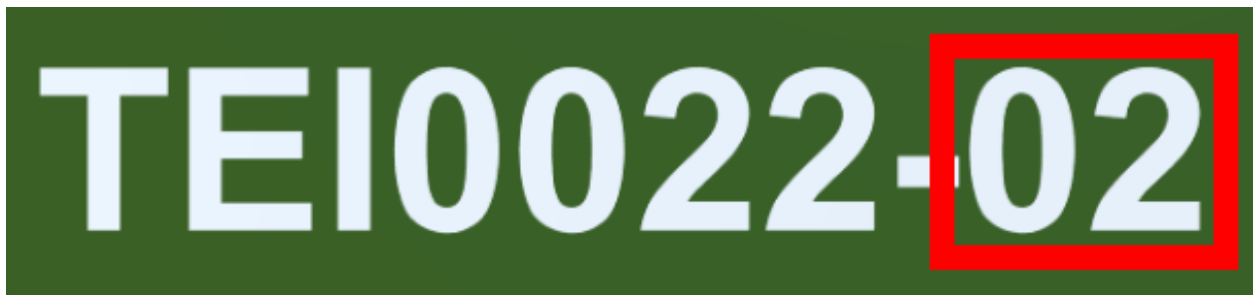


Figure 10: Board hardware revision number.

10.2 Document Change History

Date	Revision	Contributor	Description
 2020-11-03	v.54(see page 6)	Thomas Dück ⁴	typo correction
2020-11-03	v.52	ED	Update TRM to REV03
2020-06-03	v.48	TD	Chapter 'Power-On Sequence' updated
2020-02-26	v.47	ED	Update TRM to REV02

⁴ <https://wiki.trenz-electronic.de/display/~t.dueck>

Date	Revision	Contributor	Description
--	all	Antti Lukats ⁵ , ED ⁶ , Thomas Dück ⁷	Initial Document

Table 32: Document change history.

⁵ <https://wiki.trenz-electronic.de/display/~antti.lukats>

⁶ <https://wiki.trenz-electronic.de/display/~e.dyck>

⁷ <https://wiki.trenz-electronic.de/display/~t.dueck>

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 2019-06-07

⁸ <http://guidance.echa.europa.eu/>

⁹ <https://echa.europa.eu/candidate-list-table>

¹⁰ <http://www.echa.europa.eu/>